

**CHIP-PACKAGING WITH BONDING OPTIONS CONNECTED TO A  
PACKAGE SUBSTRATE**

Appl. No.	:	10/709,428	Confirmation No.	3427
Applicant	:	Cheng-Yen Huang		
Filed	:	May 5, 2004		
TC/A.U.	:	2814		
Examiner	:	TRINH, HOA B		
Docket No.	:	FTCP0035USA0		
Customer No.	:	27765		

Commissioner for Patents  
P.O. Box 1450  
Alexandria VA 22313-1450

**AMENDMENT**

5 Sir:

In response to the Office action of July 28, 2006, please amend the above-identified application as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

10 **Remarks/Arguments** begin on page 6 of this paper.